

ABSTRACT OF THE DISCLOSURE

A semiconductor device has peripheral electrode pads formed on the periphery of a semiconductor chip; 5 land pads comprising the first land pads and the second land pads formed on the semiconductor chip, and circuits formed in the semiconductor chip. The peripheral electrode pads are connected to internal circuits by internal lines. The first land pads are 10 connected to the peripheral electrode pads by rewired lines. The second electrode pads, on the other hand, are connected to the internal circuits by internal electrode pads and internal lines, not by the peripheral electrode pads.

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